PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
WAI HONG CHAN	04/21/2009

RECEIVING PARTY DATA

Name:	SUNRICH MANUFACTORY LTD.
Street Address:	14/FL., CENTURY INDUSTRIAL BLDG.
Internal Address:	SHEK PAI TAU ROAD, TMTL 192
City:	TUEN MUN, N.T.
State/Country:	HONG KONG

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29334119

CH $40.00 29334119

CORRESPONDENCE DATA

Fax Number: (914)723-4301
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 914-723-4300
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Correspondent Name: ANDREW F. YOUNG
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Address Line 4: SCARSDALE, NEW YORK 10583

ATTORNEY DOCKET NUMBER:	SUNRI.DP013
NAME OF SUBMITTER:	ANDREW F. YOUNG

Total Attachments: 3
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RECORDATION FORM COVER SHEET
PATENTS ONLY

To: Commissioner of Patents and Trademarks: Please record the attached original document or copy:

1. Name of conveying party:
Wai Hong CHAN
Additional names? _ Yes X No

2. Name and address of receiving party(ies):
Name **Sunrich Manufactory Ltd.**
Street Address: **14/Fl., Century Industrial Bldg.,**
Shek Pai Tau Road, TMTL 192
City: **Tuen Mun, N.T.**
Country: **HONG KONG**

Additional names & addresses attached? _Yes x No

3. Nature of conveyance:
X Assignment ____ Merger
_ Security Agreement ____ Change of Name
_ Other ______

Execution Date: **April 21, 2009**

4. Application number(s) or patent number(s): **29/334,119** Attorney Docket No.: **SUNRI.DP013**

If this document is being filed together with a new application, execution date of application is: ______

Patent Serial No.(s): Filing Date:

Additional numbers attached? _ Yes X No

5. Name and address of party to whom correspondence should be mailed: Address associated with **Customer No.: 28752**

Name: Andrew F. Young, Esq.
Internal Address: **Lackenbach Siegel, LLP**
Street Address: **One Chase Road**
City: **Scarsdale** State: **NY** ZIP: **10583**

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): $40.00
___ Enclosed
XX Authorized charge to **Deposit Acct No 10-0100 (Lackenbach Siegel, LLP)**

8. X Charge any additional fees in connection with this submission to our Deposit Account No. 10-0100

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

ANDREW F. YOUNG, Esq. April 23, 2009
Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and document: 3

ASSIGNMENT

In consideration of One Dollar ($1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned inventors:

Name	Address
Inventor (1): **Wai Hong CHAN**	residing at: Flat C, 19/F, Block 10 Grant Pacific Height, Palatial Coast, Siu Lam Tuen Mun, HONG KONG Citizenship: Hong Kong

declare that they are citizens of the country indicated above and with residences as listed above,

Hereby sell, assign and transfer to **Sunrich Manufactory Ltd.,** a corporation of the Country of Hong Kong, hereafter called the "Assignee," having a place of business at: 14/Fl., Century Industrial Bldg., Shek Pai Tau Road, TMTL 192, Tuen Mun, N.T., Hong Kong

To its successors, assigns and legal representatives, the entire right, title and interest for the United States and worldwide, in and to any and all improvements which are described and claimed in the

____attached specification executed on______________________,
_____specification Serial No. **29/334,119**, filed **March 20, 2009,**
______U.S. Letters Patent No. _______; issued _________________,

entitled: **WRAP AROUND BOOKLIGHT**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States or worldwide on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States or worldwide on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

The undersigned further declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

DATE 09-4-21

(L.S.)
Name: WAI HONG CHAN